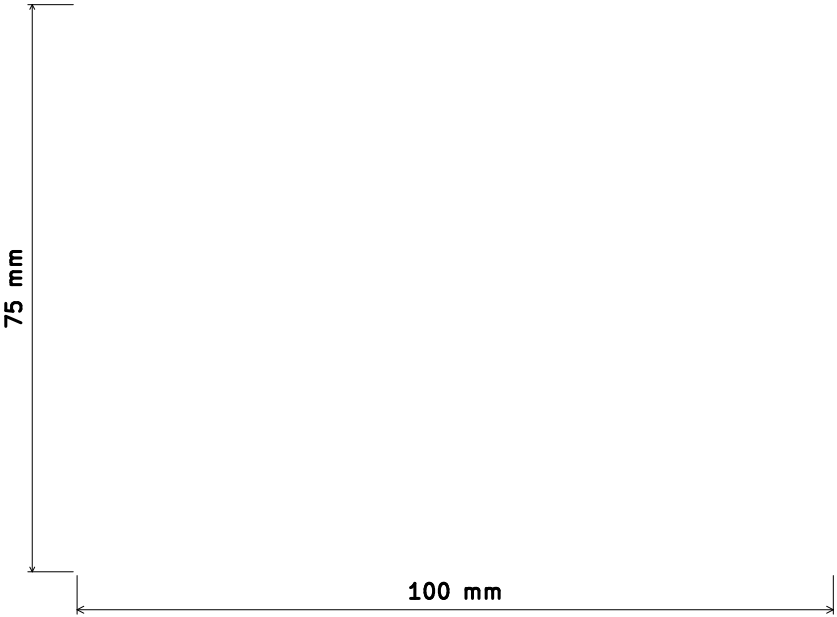


Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In1.Cu	copper		0.035 mm		1	0
Dielectric 2	core	FR4	1.24 mm	Not specified	4.5	0.02
In2.Cu	copper		0.035 mm		1	0
Dielectric 3	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6000 mm
Board overall dimensions:	100.0000 mm x 75.0000 mm		
Min track/spacing:	0.1400 mm / 0.1900 mm	Min hole diameter:	0.2000 mm
Copper Finish:	None	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



This project has not yet been verified.